

(12) United States Design Patent (10) Patent No.:

LiCalzi et al.

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(54) SYSTEM INCLUDING MULTIPLE INSTRUMENT MODULES AND ARRANGEMENT THEREOF

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U.S. Cl.

USPC **D24/216**

Field of Classification Search

USPC D24/216, 111, 127, 107, 169, 186, 217, D24/219, 223-224, 231-234; D10/46,

(Continued)

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Primary Examiner — Wan Laymon Assistant Examiner — Mark Booker

(57)**CLAIM**

The ornamental design for an system including multiple instrument modules and arrangement thereof, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of a system including multiple instrument modules and arrangement thereof in accordance with an embodiment;

FIG. 2 is a rear perspective view of a system including multiple instrument modules and arrangement thereof in accordance with an embodiment;

FIG. 3 is a front elevational view of a system including multiple instrument modules and arrangement thereof in accordance with an embodiment;

FIG. 4 is a rear elevational view of a system including multiple instrument modules and arrangement thereof in accordance with an embodiment;

FIG. 5 is a left side elevational view of a system including multiple instrument modules and arrangement thereof in accordance with an embodiment;

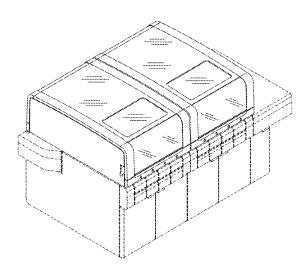
FIG. 6 is a right side elevational view of a system including multiple instrument modules and arrangement thereof in accordance with an embodiment;

FIG. 7 is a top view of a system including multiple instrument modules and arrangement thereof in accordance with an embodiment; and,

FIG. 8 is a bottom view of a system including multiple instrument modules and arrangement thereof in accordance with an embodiment.

The broken lines shown in the figures represent portions of the system including multiple instrument modules and arrangement thereof that form no part of the claimed design. The broken line showing immediately adjacent the shaded areas represents boundaries to the claimed design and forms no part of the claimed design.

1 Claim, 8 Drawing Sheets



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(58) Field of Classification Search

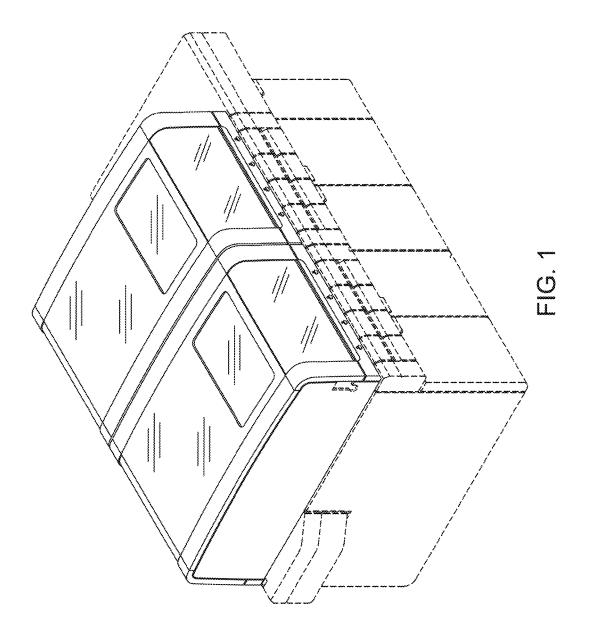
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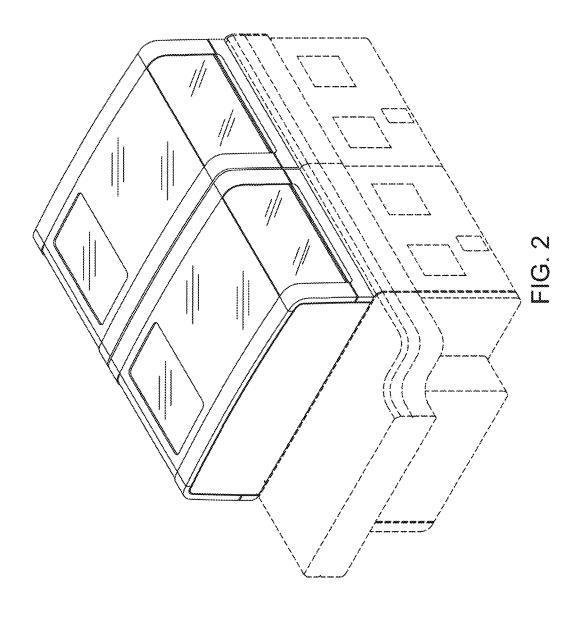
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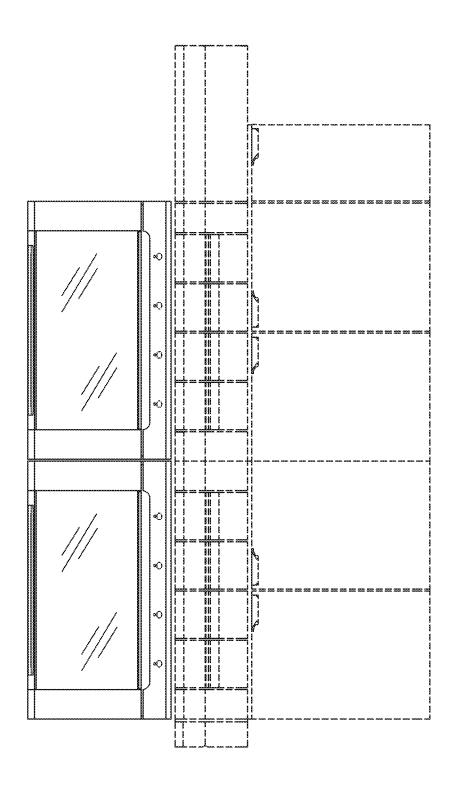
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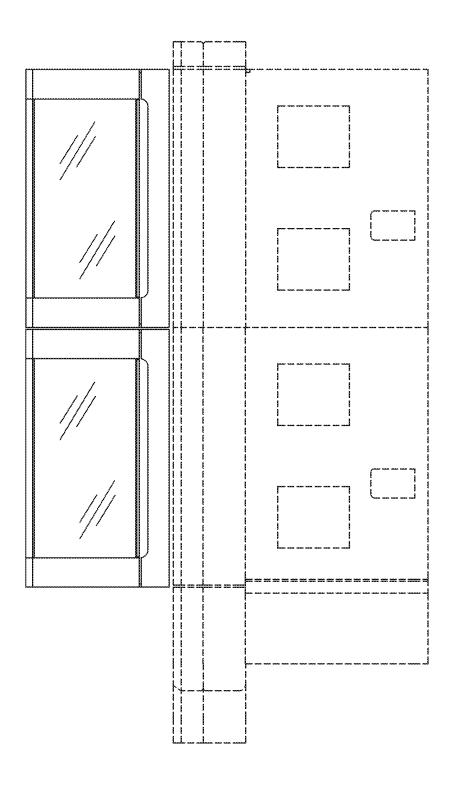
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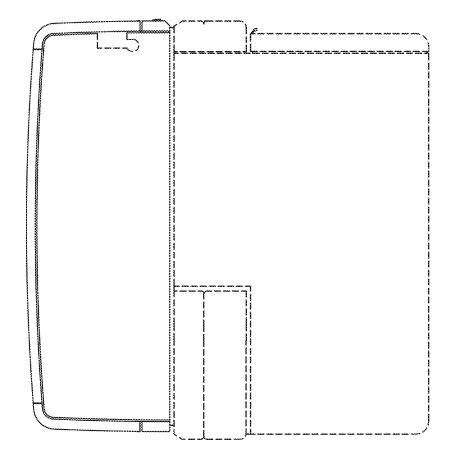
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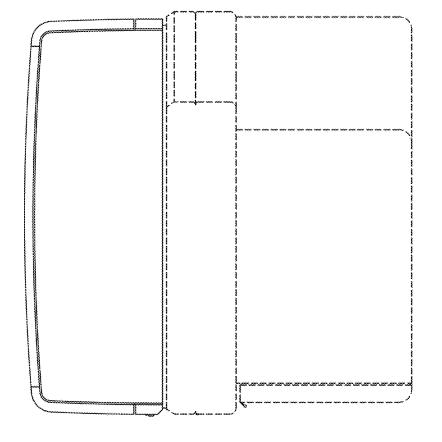




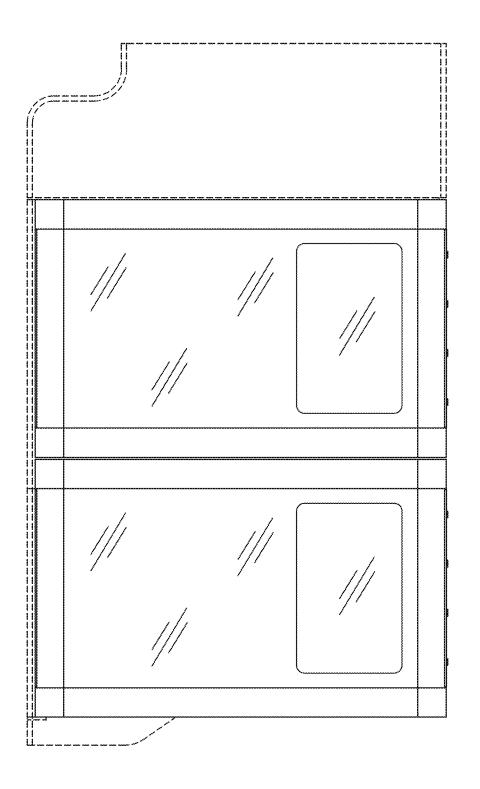


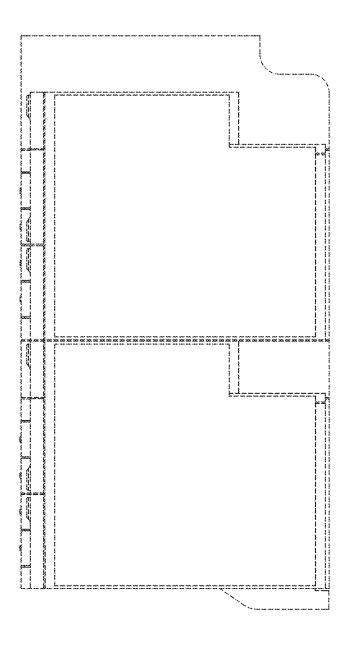






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